

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
RYOSUKE YAMAMURA	04/08/2022
YASUAKI KAKEHI	04/25/2022
KEISUKE WATANABE	04/25/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MERCARI, INC.
<b>Street Address:</b>	ROPPONGI HILLS MORI TOWER, 18TH FLOOR
<b>Internal Address:</b>	6-10-1 ROPPONGI, MINATO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	1066118
<b>Name:</b>	THE UNIVERSITY OF TOKYO
<b>Street Address:</b>	3-1, HONGO 7-CHOME, BUNKYO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	1138654
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17705164
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(650)843-4001
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	6508434000
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<b>Correspondent Name:</b>	YALEI SUN
<b>Address Line 1:</b>	MORGAN, LEWIS & BOCKIUS
<b>Address Line 2:</b>	1400 PAGE MILL ROAD
<b>Address Line 4:</b>	PALO ALTO, CALIFORNIA 94304
<b>ATTORNEY DOCKET NUMBER:</b>	122871-5015-US

<b>NAME OF SUBMITTER:</b>	YALEI SUN
<b>SIGNATURE:</b>	/Yalei Sun/
<b>DATE SIGNED:</b>	04/12/2023
<b>Total Attachments: 3</b> source=122871-5015-US Executed Assignment#page1.tif source=122871-5015-US Executed Assignment#page2.tif source=122871-5015-US Executed Assignment#page3.tif	

## COMBINED ASSIGNMENT & DECLARATION

### ASSIGNMENT

WHEREAS, I hereinafter called the "Assignor", has made the invention described in the United States patent application entitled "SENSOR", executed by Assignor on the same date as, or on a date prior to, this Assignment;

WHEREAS, Mercari, Inc., a corporation organized and existing under the laws of Japan, having a place of business at Roppongi Hills Mori Tower 18th FL, 6-10-1 Roppongi, Minato-ku, Tokyo 1066118 Japan, and The University of Tokyo, a national university organized and existing under the laws of Japan, having a place of business at 3-1, Hongo 7-chome, Bunkyo-ku, Tokyo 1138654 Japan, hereinafter called the "Assignees", desire to acquire the entire right, title and interest in and to the invention and the patent application identified above, and all patents which may be obtained for said invention, as set forth below;

NOW, THEREFORE, be it known that, for good and valuable consideration the receipt of which by the Assignor from Assignees is hereby acknowledged, the Assignor has sold, assigned and transferred, and by these presents does sell, assign and transfer to the Assignees, the entire right, title and interest for the United States in and to the invention and the patent application identified above, and any patents that may issue for said invention in the United States; together with the entire right, title and interest in and to said invention and all patent applications and patents issuing therefrom in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, renewals and extensions of any of the patent applications and patents defined above; together with the right to recover all damages, including, but not limited to, a reasonable royalty, by reason of past, present, or future infringement or any other violation of patent or patent application rights; to have and to hold for the sole and exclusive use and benefit of the Assignees, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignor hereby covenants and agrees, for both the Assignor and the Assignor's legal representatives, that the Assignor will assist the Assignees in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignees may elect to make covering the invention identified above; in vesting in the Assignees like exclusive title in and to all such other patent applications and patents; and that the Assignor will execute and deliver to the Assignees any and all additional papers which may be requested by the Assignees to carry out the terms of this Assignment.

The Commissioner of Patents and Trademarks is hereby authorized and requested to issue patents to the Assignees in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignor has executed this agreement.

**DECLARATION**

As the below-named inventor, I hereby declare that:

This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

I acknowledge my duty to disclose to the United States Patent and Trademark Office all information that I know to be material to the patentability of this application as defined in 37 C.F.R. § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Further, I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application and any patent issued thereon.

Date April 8, 2022

Ryosuke Yamamura L.S.  
**Ryosuke YAMAMURA**

Date \_\_\_\_\_

\_\_\_\_\_ L.S.  
**Yasuaki KAKEHI**

Date \_\_\_\_\_

\_\_\_\_\_ L.S.  
**Keisuke WATANABE**

IN TESTIMONY WHEREOF, the Assignor has executed this agreement.

**DECLARATION**

As the below-named inventor, I hereby declare that:

This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

I acknowledge my duty to disclose to the United States Patent and Trademark Office all information that I know to be material to the patentability of this application as defined in 37 C.F.R. § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

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Date \_\_\_\_\_

\_\_\_\_\_  
Ryosuke YAMAMURA L.S.

Date 25 Apr, 2022

*Yasuaki Kakehi*  
Yasuaki KAKEHI L.S.

Date 25 Apr 2022

*Keisuke Watanabe*  
Keisuke WATANABE L.S.